MIXIM

2.5Gbps, Low-Power, +3.3V Clock Recovery and Data Retiming IC

General Description

The MAX3875 is a compact, low-power clock recovery and data retiming IC for 2.488Gbps SDH/SONET applications. The fully integrated phase-locked loop recovers a synchronous clock signal from the serial NRZ data input, which is retimed by the recovered clock. Differential PECL-compatible outputs are provided for both clock and data signals, and an additional 2.488Gbps serial input is available for system loopback diagnostic testing. The device also includes a TTL-compatible loss-of-lock (LOL) monitor.

The MAX3875 is designed for both section-regenerator and terminal-receiver applications in OC-48/STM-16 transmission systems. Its jitter performance exceeds all of the SONET/SDH specifications.

This device operates from a single +3.3V to +5.0V supply over a -40°C to +85°C temperature range. The typical power consumption is only 400mW with a +3.3V supply. It is available in a 32-pin TQFP package, as well as in die form.

Applications

SDH/SONET Receivers and Regenerators
Add/Drop Multiplexers
Digital Cross-Connects
2.488Gbps ATM Receiver
Digital Video Transmission

SDH/SONET Test Equipment

Features

- Exceeds ANSI, ITU, and Bellcore SONET/SDH Regenerator Specifications
- ♦ 400mW Power Dissipation (at +3.3V)
- ♦ Clock Jitter Generation: 0.003UIRMS
- ♦ Single +3.3V or +5V Power Supply
- Fully Integrated Clock Recovery and Data Retiming
- Additional High-Speed Input Facilitates System Loopback Diagnostic Testing
- ♦ Tolerates >2000 Consecutive Identical Digits
- ♦ Loss-of-Lock Indicator
- Differential PECL-Compatible Data and Clock Outputs

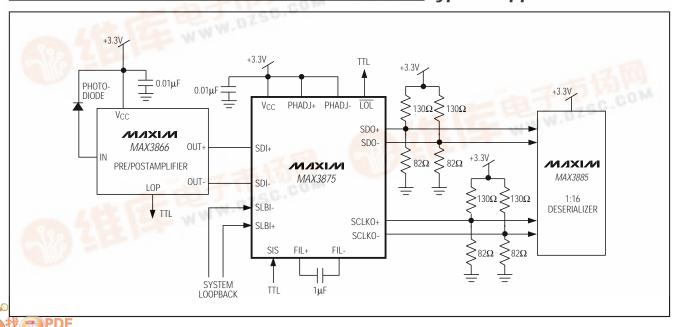
Ordering Information

PART	TEMP. RANGE	PIN-PACKAGE
MAX3875EHJ	-40°C to +85°C	32 TQFP
MAX3875E/D	-40°C to +85°C	Dice*

^{*} Dice are designed to operate over this range, but are tested and guaranteed at T_A = +25°C only. Contact factory for availability.

Pin Configuration appears at end of data sheet.

Typical Application Circuit



Maxim Integrated Products

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V _{CC} 0.5V to +7.0V
Input Voltage Levels
(SDI+, SDI-, SLBI+, SLBI-)(V _{CC} - 0.5V) to (V _{CC} + 0.5V)
Input Current Levels (SDI+, SDI-, SLBI+, SLBI-)±10mA
PECL Output Voltage
(SDO+, SDO-, SCLKO+, SCLKO-)(V _{CC} + 0.5V)
PECL Output Current, (SDO+, SDO-, SCLKO+, SCLKO-)56mA
Voltage at LOL, SIS, PHADJ+, PHADJ-,
FII + FII0.5V to (V cc + 0.5V)

Continuous Power Dissipation ($T_A = +85^{\circ}C$) TQFP (derate 16.1mW/°C above +85°C)	1.0W
Operating Temperature Range	
MAX3875EHJ	40°C to +85°C
Operating Junction Temperature (die)	55°C to +150°C
Storage Temperature Range	
Processing Temperature (die)	
Lead Temperature (soldering, 10sec)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +3.0V \text{ to } +5.5V, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at +3.3V and $T_A = +25^{\circ}\text{C}.)$ (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN T	YP MAX	UNITS	
Supply Current	Icc	Excluding PECL output termination	1	22 167	mA	
Differential Input Voltage (SDI±, SLBI±)	V _{ID}	Figure 1	50	800	mVp-p	
Single-Ended Input Voltage (SDI±, SLBI±)	VIS		V _{CC} - 0.4	V _{CC} + 0.2	V	
Input Termination to V _{CC} (SDI±, SLBI±)	RIN		45		Ω	
PECL Output High Voltage	Voн	$T_A = 0^{\circ}C \text{ to } +85^{\circ}C$	V _{CC} - 1.025	V _{CC} - 0.88	V	
(SDO±, SCLKO±)	VOH	$T_A = -40^{\circ}C$	V _{CC} - 1.085	V _{CC} - 0.88	V	
PECL Output Low Voltage	Vai	$T_A = 0^{\circ}C \text{ to } +85^{\circ}C$	V _{CC} - 1.81	V _{CC} - 1.62	V	
(SDO±, SCLKO±)	V _{OL}	T _A = -40°C	V _{CC} - 1.83	V _{CC} - 1.555	\ \ \	
TTL Input High Voltage (SIS)	VIH		2.0		V	
TTL Input Low Voltage (SIS)	VIL			0.8	V	
TTL Input Current (SIS)			-10	+10	μΑ	
TTL Output High Voltage (LOL)	Voн		2.4	V _C C	V	
TTL Output Low Voltage (LOL)	VoL			0.4	V	

Note 1: Dice are tested at $T_A = +25$ °C only.

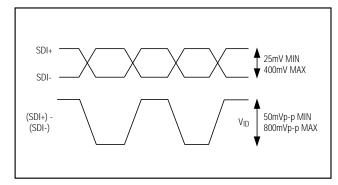


Figure 1. Input Amplitude

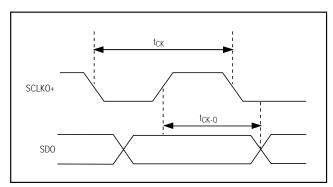


Figure 2. Output Clock-to-Q Delay

AC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +3.0 \text{V to } +5.5 \text{V}, T_A = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C}, \text{ unless otherwise noted.}$ Typical values are at +3.3 V and $T_A = +25 ^{\circ}\text{C}.)$ (Note 2)

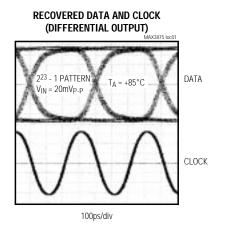
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Serial Output Clock Rate				2.488		Gbps	
Clock-to-Q Delay		Figure 2	110		290	ps	
Jitter Peaking	Jp	f ≤ 2MHz			0.1	dB	
Jitter Transfer Bandwidth	J _{BW}			1.1	2.0	MHz	
		f = 70kHz	1.91	3.6			
Jitter Tolerance		f = 100kHz	1.76	2.75		Illnn	
		f = 1MHz	0.41	0.67		· UIp-p	
		f = 10MHz (Note 3)	0.21	0.45			
Jitter Generation	losu	Jitter BW = 12kHz to 20MHz		0.003	0.006	UI _{RMS}	
Jitter Generation	JGEN			0.026	0.056	Ulp-p	
Clock Output Edge Speed		20% to 80%		70		ps	
Data Output Edge Speed		20% to 80%		108		ps	
Tolerated Consecutive Identical Digits				2000		Bits	
Input Return Loss		100kHz to 2.5GHz		-17		dB	
(SDI±, SLBI±)		2.5GHz to 4.0GHz		-15		UD	

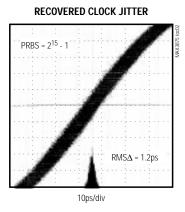
Note 2: AC characteristics are guaranteed by design and characterization.

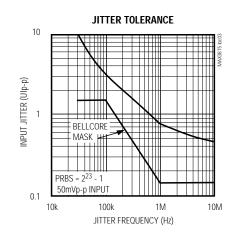
Note 3: See Typical Operating Characteristics for worst-case distribution.

Typical Operating Characteristics

 $(V_{CC} = +3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$

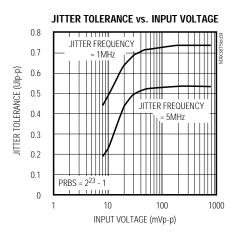


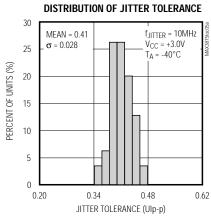


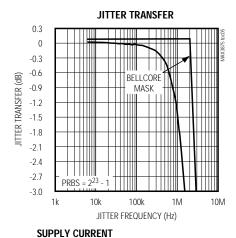


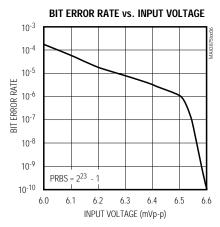
Typical Operating Characteristics (continued)

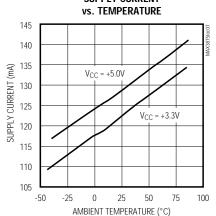
 $(V_{CC} = +3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$











Pin Description

PIN	NAME	FUNCTION
1, 2, 8, 9, 10, 16, 26, 29, 32	GND	Supply Ground
3, 6, 11, 14, 15, 17, 20, 21, 24	Vcc	Positive Supply Voltage
4	SDI+	Positive Data Input. 2.488Gbps serial data stream.
5	SDI-	Negative Data Input. 2.488Gbps serial data stream.
7	SIS	Signal Input Selection, TTL. Low for normal data input. High for system loopback input.
12	SLBI+	Positive System Loopback Input. 2.488Gbps serial data stream.
13	SLBI-	Negative System Loopback Input. 2.488Gbps serial data stream.
18	SCLKO-	Negative Serial Clock Output, PECL, 2.488GHz. SDO- is clocked out on the falling edge of SCLKO

Pin Description (continued)

PIN	NAME	FUNCTION
19	SCLKO+	Positive Serial Clock Output, PECL, 2.488GHz. SDO+ is clocked out on the rising edge of SCLKO+.
22	SDO-	Negative Data Output, PECL compatible, 2.488Gbps
23	SDO+	Positive Data Output, PECL compatible, 2.488Gbps
25	LOL	Loss-of-Lock Output, TTL, PLL loss-of-lock monitor, active low (internal 10kΩ pull-up resistor)
27	PHADJ-	Negative Phase-Adjust Input. Used to optimally align internal PLL phase. Connect to V _{CC} if not used.
28	PHADJ+	Positive Phase-Adjust Input. Used to optimally align internal PLL phase. Connect to V _{CC} if not used.
30	FIL-	Negative Filter Input. PLL loop filter connection. Connect a 1.0μF capacitor between FIL+ and FIL
31	FIL+	Positive Filter Input. PLL loop filter connection. Connect a 1.0µF capacitor between FIL+ and FIL

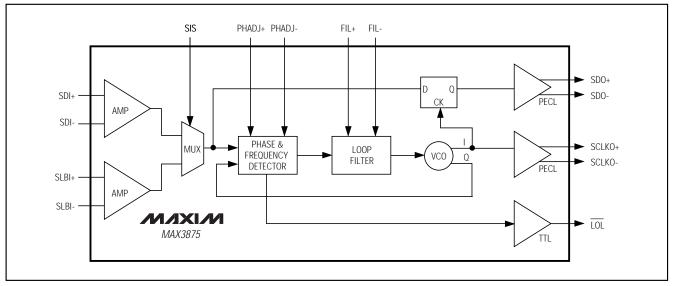


Figure 3. Functional Diagram

Detailed Description

The MAX3875 consists of a fully integrated phase-locked loop (PLL), input amplifier, data retiming block, and PECL output buffer (Figure 3). The PLL consists of a phase/frequency detector (PFD), a loop filter, and a voltage-controlled oscillator (VCO).

This device is designed to deliver the best combination of jitter performance and power dissipation by using a fully differential signal architecture and low-noise design techniques.

Input Amplifier

Input amplifiers are implemented for both the main data and system loopback inputs. These amplifiers accept a differential input amplitude from 50mVp-p up to 800mVp-p. The bit error rate is better than $1 \cdot 10^{-10}$ for input signals as small as 10mVp-p, although the jitter tolerance performance will be degraded. For interfacing with PECL signal levels, see *Applications Information*.

Phase Detector

The phase detector incorporated in the MAX3875 produces a voltage proportional to the phase difference between the incoming data and the internal clock. Because of its feedback nature, the PLL drives the error voltage to zero, aligning the recovered clock to the center of the incoming data eye for retiming. The external phase adjust pins (PHADJ+, PHADJ-) allow the user to vary the internal phase alignment.

Frequency Detector

The digital frequency detector (FD) aids frequency acquisition during start-up conditions. The frequency difference between the received data and the VCO clock is derived by sampling the in-phase and quadrature VCO outputs on both edges of the data input signal. Depending on the polarity of the frequency difference, the FD drives the VCO until the frequency difference is reduced to zero. Once frequency acquisition is complete, the FD returns to a neutral state. False locking is completely eliminated by this digital frequency detector.

Loop Filter and VCO

The phase detector and frequency detector outputs are summed into the loop filter. An external capacitor, C_F, is required to set the PLL damping ratio. Refer to *Design Procedure* for guidelines on selecting this capacitor.

The loop filter output controls the on-chip LC VCO running at 2.488GHz. The VCO provides low phase noise and is trimmed to the correct frequency. Clock jitter generation is typically 1.2psRMs within a jitter bandwidth of 12kHz to 20MHz.

Loss-of-Lock Monitor

A loss-of-lock ($\overline{\text{LOL}}$) monitor is incorporated in the MAX3875 frequency detector. A loss-of-lock condition is signaled immediately with a TTL low. When the PLL is frequency locked, $\overline{\text{LOL}}$ switches to TTL high in approximately 800ns.

Note that the $\overline{\text{LOL}}$ monitor is only valid when a data stream is present on the inputs to the MAX3875. As a result, $\overline{\text{LOL}}$ does not detect a loss-of-power condition resulting from a loss of the incoming signal.

Design Procedure

Setting the Loop Filter

The MAX3875 is designed for both regenerator and receiver applications. Its fully integrated PLL is a classic second-order feedback system, with a loop bandwidth (fL) fixed at 1.1MHz. The external capacitor, CF, can be adjusted to set the loop damping. Figures 4 and 5 show the open-loop and closed-loop transfer functions.

The PLL zero frequency, fz, is a function of external capacitor C_F, and can be approximated according to:

$$f_Z = \frac{1}{2\pi(60) C_F}$$

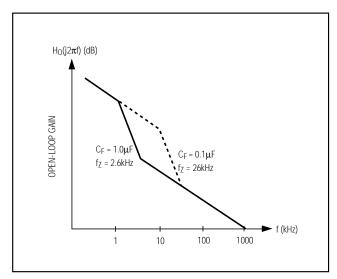


Figure 4. Open-Loop Transfer Function

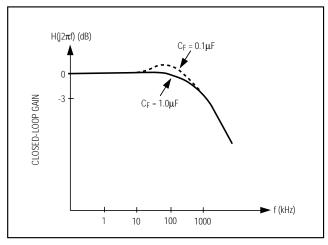


Figure 5. Closed-Loop Transfer Function

For an overdamped system (f_Z/f_L) < 0.25, the jitter peaking (Mp) of a second-order system can be approximated by:

$$M_p = 20 \log \left(1 + \frac{f_z}{f_L} \right)$$

For example, using $C_F = 0.1 \mu F$ results in a jitter peaking of 0.2dB. Reducing C_F below 0.01 μF may result in PLL instability. The recommended value for $C_F = 1.0 \mu F$ to guarantee a maximum jitter peaking of less than 0.1dB. C_F must be a low TC, high-quality capacitor of type X7R or better.

Input and Output Terminations

The MAX3875's digital outputs (SDO+, SDO-, SCLKO+, SCLKO-) are designed to interface with PECL signal levels. It is important to bias these ports appropriately. A circuit that provides a Thevenin equivalent of 50Ω to VCC - 2V can be used with fixed impedance transmission lines for proper termination. To ensure best performance, the differential outputs must have balanced loads. The input termination can be driven differentially, or can be driven single-ended by externally biasing SDI- or SLBI- to the center of the voltage swing.

Jitter Tolerance and Input Sensitivity Trade-Offs

When the received data amplitude is higher than 50mVp-p, the MAX3875 provides a typical jitter tolerance of 0.45UI at jitter frequencies greater than 10MHz. The SDH/SONET jitter tolerance specification is 0.15UI, leaving a jitter allowance of 0.3UI for receiver preamplifier and postamplifier design.

The BER is better than 1 • 10⁻¹⁰ for input signals greater than 10mVp-p. At 10mVp-p, jitter tolerance will be degraded, but will still be above the SDH/SONET requirement. The user can make a trade-off between jitter tolerance and input sensitivity according to the specific application. Refer to the *Typical Operating Characteristics* for Jitter Tolerance and BER vs. Input Amplitude graphs.

_Applications Information

Consecutive Identical Digits (CID)

The MAX3875 has a low phase and frequency drift in the absence of data transitions. As a result, long runs of consecutive zeros and ones can be tolerated while maintaining a BER of 1 • 10-10. The CID tolerance is tested using a 2¹³ - 1 PRBS, substituting a long run of zeros to simulate the worst case. A CID tolerance of 2000 bits is typical.

Phase Adjust

The internal clock is aligned to the center of the data eye. For specific applications this sampling position can be shifted using the PHADJ inputs to optimize BER performance. The PHADJ inputs operate with differential input voltages up to ± 1.5 V. A simple resistor-divider with a bypass capacitor is sufficient to set these levels. When the PHADJ inputs are not used, they should be tied directly to VCC.

System Loopback

The MAX3875 is designed to allow system loopback testing. The user can connect a serializer output in a transceiver directly to the SLBI+ and SLBI- inputs of the MAX3875 for system diagnostics. To select the SLBI± inputs, apply a TTL logic high to the SIS pin.

PECL Input Levels

When interfacing with differential PECL input levels, it is important to attenuate the signal while still maintaining 50Ω termination (Figure 6). AC coupling is also required to maintain the input common-mode level.

Layout

The MAX3875's performance can be significantly affected by circuit board layout and design. Use good high-frequency design techniques, including minimizing ground inductance and using fixed-impedance transmission lines on the data and clock signals. Power-supply decoupling should be placed as close to VCC as possible. Take care to isolate the input from the output signals to reduce feedthrough.

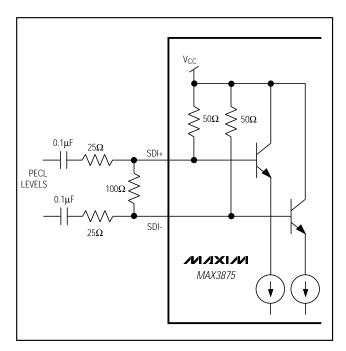
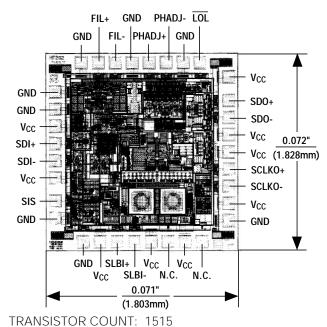


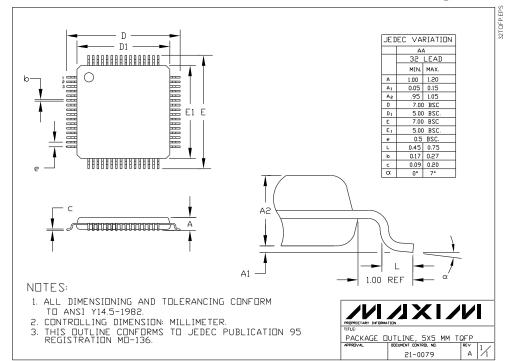
Figure 6. PECL Input Interface

Pin Configuration TOP VIEW PHAD). GND GND GND 24 V_{CC} 23 SDO+ GND 22 SD0-V_{CC} 3 SDI+ 4 21 V_{CC} MAX3875 20 V_{CC} SDI- 5 19 SCLKO+ V_{CC} 6 SIS 7 18 SCLKO-GND 8 17 V_{CC} GND SLBI+ SLBI-Vcc Vcc **TQFP**

_Chip Topography



Package Information



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

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